SN54ALS576B, SN54AS576 SN74ALS576B, SN74ALS577A, SN74AS576 OCTAL D-TYPE EDGE-TRIGGERED FLIP-FLOPS WITH 3-STATE OUTPUTS

SDAS065B – DECEMBER 1982 – REVISED JANUARY 1995

- 3-State Buffer-Type Inverting Outputs Drive Bus Lines Directly
- Bus-Structured Pinout
- Buffered Control Inputs
- SN74ALS577A Has Synchronous Clear
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), Standard Plastic (N, NT) and Ceramic (J) 300-mil DIPs, and Ceramic Flat (W) Packages

description

These octal D-type edge-triggered flip-flops feature 3-state outputs designed specifically for bus driving. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

These flip-flops enter data on the low-to-high transition of the clock (CLK) input.

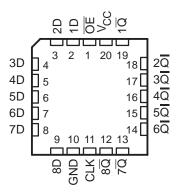
The output-enable (\overline{OE}) input does not affect internal operations of the flip-flops. Old data can be retained or new data can be entered while the outputs are disabled.

The SN54ALS576B and SN54AS576 are characterized for operation over the full military temperature range of -55° C to 125° C. The SN74ALS576B, SN74ALS577A, and SN74AS576 are characterized for operation from 0° C to 70° C.

SN54ALS576B, SN54AS576 J OR W PACKAGE
SN74ALS576B, SN74AS576 DW OR N PACKAGE
(TOP VIEW)

	(,	
OE 1D 2D 3D 4D 5D 6D 7D	1 2 3 4 5 6 7 8	20 19 18 17 16 15 14 13] V _{CC}] 1Q] 2Q] 3Q] 3Q] 4Q] 5Q] 6Q] 7Q
6D [7	14] 6 <mark>Q</mark>
7D [8D [GND [8 9 10	13 12 11] 7 <u>Q</u>] 8Q] CLK

SN54ALS576B, SN54AS576...FK PACKAGE (TOP VIEW)



SN74ALS577A . . . DW OR NT PACKAGE (TOP VIEW)

CLR [1	O_{24}	V _{CC}
OE [2	23	NC
1D [3	22	1Q
2D [4	21	2 <mark>Q</mark>
3D [5	20	3Q
4D [19	4Q
5D [7	18	5Q
6D (8	17	6Q
7D [9	16	7Q
8D [10	15	8Q
NC	11	14	CLK
GND	12	13	NC

NC - No internal connection

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



SN54ALS576B, SN54AS576 SN74ALS576B, SN74ALS577A, SN74AS576 OCTAL D-TYPE EDGE-TRIGGERED FLIP-FLOPS WITH 3-STATE OUTPUTS SDAS065B - DECEMBER 1982 - REVISED JANUARY 1995

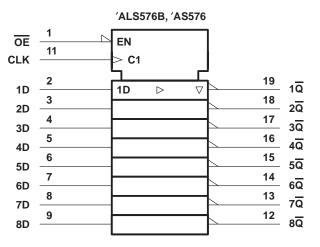
Function Tables

(each flip-flop)										
OE	CLK	D	Q							
L	\uparrow	Н	L							
L	\uparrow	L	н							
L	L	Х	\overline{Q}_0							
Н	Х	Х	Z							

SN74ALS577A (each flip-flop)

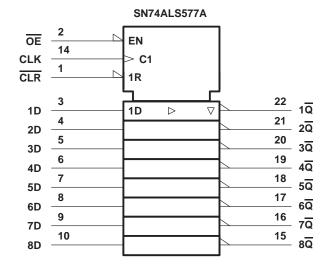
	INP	UTS		OUTPUT
OE	CLR	CLK	D	Q
L	L	\uparrow	Х	Н
L	Н	\uparrow	Н	L
L	Н	\uparrow	L	н
L	Н	L	Х	\overline{Q}_0
н	Х	Х	Х	Z





[†] These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown for the 'ALS576B and 'AS576 are for the DW, J, N, and W packages.



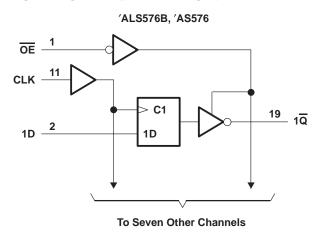
Pin numbers shown for the SN74ALS577A are for the DW and NT packages.

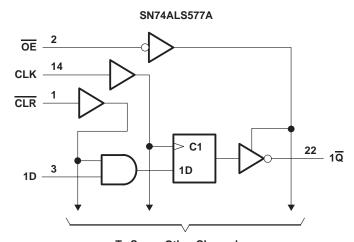


SN54ALS576B, SN54AS576 SN74ALS576B, SN74ALS577A, SN74AS576 **OCTAL D-TYPE EDGE-TRIGGERED FLIP-FLOPS WITH 3-STATE OUTPUTS**

SDAS065B - DECEMBER 1982 - REVISED JANUARY 1995

logic diagrams (positive logic)





Pin numbers shown are for the DW, J, N, and W packages.

To Seven Other Channels

Pin numbers shown are for the DW and NT packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC}	
Voltage applied to a disabled 3-state output	5.5 V
Operating free-air temperature range, T _A : SN54ALS576B	
SN74ALS576B, SN74ALS577A	0°C to 70°C
Storage temperature range	-65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions Г

			SN	54ALS57	76B	SN74ALS576B SN74ALS577A		UNIT	
			MIN	NOM	MAX	MIN	NOM	MAX	
Vcc	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.7			0.8	V
ЮН	High-level output current				-1			-2.6	mA
IOL	Low-level output current				12			24	mA
4		'ALS576B	0		22	0		30	MHz
fclock	Clock frequency	SN74ALS577A				0		30	
1	Dulas duration	'ALS576B, CLK high or low	25			16.5			
tw	Pulse duration	SN74ALS577A, CLK high or low				16.5			ns
		Data	15			15			
t _{su}	Setup time before CLK [↑]	SN74ALS577A CLR				15			ns
		Data	4			0			
th	Hold time after CLK↑	SN74ALS577A CLR				0			ns
Тд	Operating free-air temperature		-55		125	0		70	°C



T

SN74AL S576B

SN54ALS576B, SN54AS576 SN74ALS576B, SN74ALS577A, SN74AS576 OCTAL D-TYPE EDGE-TRIGGERED FLIP-FLOPS WITH 3-STATE OUTPUTS SDAS065B - DECEMBER 1982 - REVISED JANUARY 1995

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST C	ST CONDITIONS		4ALS57	'6B	-	4ALS57 4ALS57	-	UNIT
			MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	
VIK	$V_{CC} = 4.5 V,$	lj = -18 mA			-1.2			-1.2	V
	$V_{CC} = 4.5 V \text{ to } 5.5 V,$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	2		V _{CC} -2	2		
VOH	V _{CC} = 4.5 V	$I_{OH} = -1 \text{ mA}$	2.4	3.3					V
	$v_{CC} = 4.5 v$	I _{OH} = -2.6 mA				2.4	3.2		
		I _{OL} = 12 mA		0.25	0.4		0.25	0.4	V
VOL	$V_{CC} = 4.5 V$	I _{OL} = 24 mA					0.35	0.5	v
IOZH	V _{CC} = 5.5 V,	V _O = 2.7 V			20			20	μA
IOZL	$V_{CC} = 5.5 V,$	$V_{O} = 0.4 V$			-20			-20	μA
lj	V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA
Iн	V _{CC} = 5.5 V,	VI = 2.7 V			20			20	μΑ
١ _{IL}	V _{CC} = 5.5 V,	VI = 0.4 V			-0.2			-0.2	mA
IO‡	V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA
		Outputs high		10	18		10	18	
ICC	V _{CC} = 5.5 V	Outputs low		15	24		15	24	mA
		Outputs disabled		16	30		16	30	

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. [‡] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)		(V _{CC} = 4.5 C _L = 50 pl R1 = 500 <u>0</u> R2 = 500 <u>0</u> T _A = MIN 1	; , 2, 2,			UNIT
			SN54AL	S576B	SN74AL	S576B	SN74AL	S577A	
			MIN	MAX	MIN	MAX	MIN	MAX	
fmax			22		30		30		MHz
^t PLH	CLK	Any O	4	24	3	14	4	14	ns
^t PHL	OLK	Any Q	4	20	4	14	4	14	115
^t PZH	OE	Am. 0	4	24	3	18	4	18	ns
^t PZL	OE	Any Q	3	23	4	18	4	18	115
^t PHZ	OE	Any Q	2	14	1	10	2	10	ns
^t PLZ		Any Q	3	29	2	15	3	15	115

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



SN54ALS576B, SN54AS576 SN74ALS576B, SN74ALS577A, SN74AS576 OCTAL D-TYPE EDGE-TRIGGERED FLIP-FLOPS WITH 3-STATE OUTPUTS SDAS065B – DECEMBER 1982 – REVISED JANUARY 1995

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC}	
Input voltage, V _I	7V
Voltage applied to a disabled 3-state output	5.5 V
Operating free-air temperature range, T _A : SN54AS576	-55°C to 125°C
SN74AS576	0°C to 70°C
Storage temperature range	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

			SI	SN54AS576			SN74AS576		
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.8			0.8	V
IOH	High-level output current	High-level output current			-12			-15	mA
IOL	Low-level output current				32			48	mA
fclock*	Clock frequency		0		100	0		125	MHz
* *	Pulse duration	CLK high	5			4			20
t _w *	Fuise duration	CLK low	4			2			ns
t _{su} *	Setup time, data before CLK [↑]		3			2			ns
t _h *	Hold time, data after CLK↑		3			2			ns
TA	Operating free-air temperature		-55		125	0		70	°C

* On products compliant to MIL-STD-883, Class B, this parameter is based on characterization data but is not production tested.



SN54ALS576B, SN54AS576 SN74ALS576B, SN74ALS577A, SN74AS576 OCTAL D-TYPE EDGE-TRIGGERED FLIP-FLOPS WITH 3-STATE OUTPUTS SDAS065B - DECEMBER 1982 - REVISED JANUARY 1995

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CO	NDITIONS	SN	154AS57	76	SN	174AS57	′ 6	UNIT
PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	MIN	TYP†	MAX	UNIT
VIK		V _{CC} = 4.5 V,	lı = – 18 mA			-1.2			-1.2	V
		V_{CC} = 4.5 V to 5.5 V,	$I_{OH} = -2 \text{ mA}$	V _{CC} -2	2		V _{CC} -2	2		
Vон			$I_{OH} = -12 \text{ mA}$	2.4	3.2					V
		$V_{CC} = 4.5 V$	$I_{OH} = -15 \text{ mA}$				2.4	3.3		
Vei		$\lambda = 45 \lambda$	I _{OL} = 32 mA		0.29	0.5				V
VOL		$V_{CC} = 4.5 V$	I _{OL} = 48 mA					0.33	0.5	v
IOZH		V _{CC} = 5.5 V,	V _O = 2.7 V			50			50	μΑ
IOZL		V _{CC} = 5.5 V,	V _O = 0.4 V			-50			-50	μΑ
Ιį		V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA
Iн		V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μA
L.	D		<u>)/. 04)/</u>			-3			-2	mA
ΙL	All others	V _{CC} = 5.5 V,	$V_{ } = 0.4 V$			-0.5			-0.5	mA
10‡	-	V _{CC} = 5.5 V,	V _O = 2.25 V	-30		-112	-30		-112	mA
			Outputs high		77	125		77	125	
ICC		V _{CC} = 5.5 V	Outputs low		84	135		84	135	mA
			Outputs disabled		84	135		84	135	

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

switching characteristics (see Figure 1)

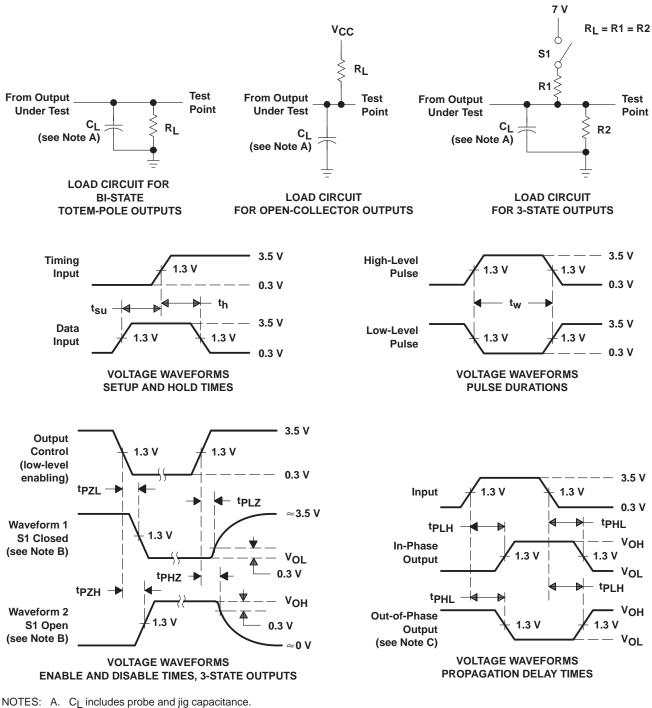
PARAMETER	FROM (INPUT)	TO (OUTPUT)	ν ₍ C _L R1 R2 Τ _Α	UNIT			
			SN54AS576		SN74AS576		
			MIN	MAX	MIN	MAX	
fmax*			100		125		MHz
^t PLH	CLK	Any Q	3	11	3	8	ns
^t PHL	GLR	Any Q	4	11	4	9	115
^t PZH	OE	Any O	2	7	2	6	ns
tPZL	UE	Any Q	3	11	3	10	115
^t PHZ	OE	Any Q	2	7	2	6	ns
^t PLZ		Any Q	2	7	2	6	

* On products compliant to MIL-STD-883, Class B, this parameter is based on characterization data but is not production tested. § For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



SN54ALS576B, SN54AS576 SN74ALS576B, SN74ALS577A, SN74AS576 **OCTAL D-TYPE EDGE-TRIGGERED FLIP-FLOPS WITH 3-STATE OUTPUTS** SDAS065B - DECEMBER 1982 - REVISED JANUARY 1995

PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control. C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: $PRR \le 1$ MHz, $t_f = t_f = 2$ ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



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18-Sep-2008

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	n MSL Peak Temp ⁽³⁾
84001022A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
8400102RA	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
8400102SA	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type
SN54ALS576BJ	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SN54AS576J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SN74ALS576BDW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS576BDWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS576BDWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS576BDWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS576BDWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS576BDWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS576BN	ACTIVE	PDIP	Ν	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS576BN3	OBSOLETE	PDIP	Ν	20		TBD	Call TI	Call TI
SN74ALS576BNE4	ACTIVE	PDIP	Ν	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS576BNSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS576BNSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS576BNSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS577ADW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS577ADWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS577ADWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS577ADWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS577ADWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS577ADWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS577ANSR	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS577ANSRE4	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS577ANSRG4	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS577ANT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74ALS577ANT3	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI
SN74ALS577ANTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS576DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS576DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS576DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS576DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS576DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS576DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS576N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS576NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ54ALS576BFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54ALS576BJ	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54ALS576BW	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type
SNJ54AS576FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54AS576J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. **TBD**: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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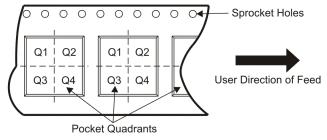
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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

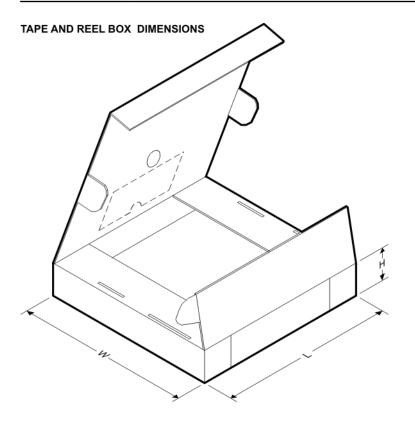


Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS576BDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ALS576BNSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74ALS577ADWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
SN74ALS577ANSR	SO	NS	24	2000	330.0	24.4	8.2	15.4	2.5	12.0	24.0	Q1
SN74AS576DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1



PACKAGE MATERIALS INFORMATION

5-Aug-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS576BDWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74ALS576BNSR	SO	NS	20	2000	346.0	346.0	41.0
SN74ALS577ADWR	SOIC	DW	24	2000	346.0	346.0	41.0
SN74ALS577ANSR	SO	NS	24	2000	346.0	346.0	41.0
SN74AS576DWR	SOIC	DW	20	2000	346.0	346.0	41.0

MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



MLCC006B - OCTOBER 1996

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within Mil-Std 1835 GDFP2-F20



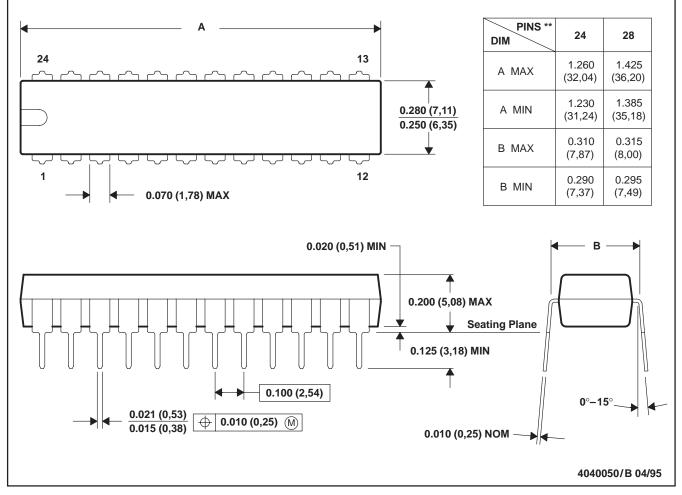
MECHANICAL DATA

MPDI004 - OCTOBER 1994

NT (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

24 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters). B. This drawing is subject to change without notice.



DW (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AD.



DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AC.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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